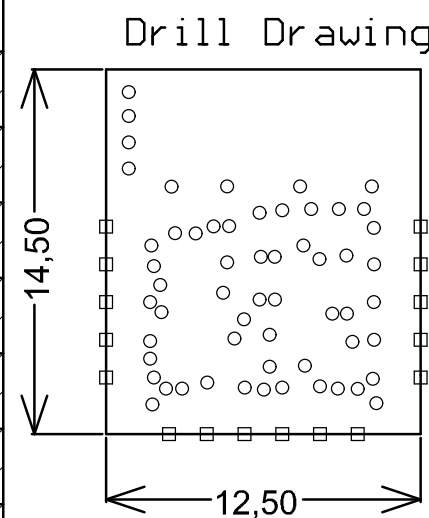


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer1	Copper	0,035mm		
4	Dielectric2	FR4	0,800mm	4,2	
5	Bottom Layer2	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
○	58	0,200mm (7,87mil)	PTH	Round	Top Layer1 - Bottom Layer2	Via	Rounded
□	16	0,600mm (23,62mil)	PTH	Round	Top Layer1 - Bottom Layer2	Pad	Rounded
	74 Total						



	ENGINEER: AXHA	TITLE: DA14531/D2632 Module	
	PCB DESIGNER: AXHA		
	DATE: 2019-12-10	PART NO.: 376-23-B	REV.: B
	FILE NAME: PCB-376-23-B.PcbDoc	DWG NO.: DD-376-23-B	SCALE: